

PCN Number:	20220627000.2	PCN Date:	June 29, 2022
Title:	Qualification of CFAB as an additional Fab site options for select LBC3S devices		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Dec 29, 2022	Sample requests accepted until:	July 29, 2022*

***Sample requests received after July 29, 2022 will not be supported.**

Change Type:

<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input checked="" type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change		

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of its CFAB fabrication facilities as an additional Wafer Fab option for the devices listed in the "Product Affected" section.

Current Fab Site			New Fab Site		
Fab Site	Process	Wafer Diameter	Fab Site	Process	Wafer Diameter
DL-LIN	LBC3S	150 mm	CFAB	LBC3S	200 mm
DL-LIN	LBC3S	200 mm			

Qual details are provided in the Qual Data Section.

Reason for Change:

These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DL-LIN	DLN	USA	Dallas
CFAB	CU3	CHN	Chengdu

Sample product shipping label (not actual product label):

TEXAS INSTRUMENTS
 MADE IN: Malaysia
 2DC: 20:
 MSL 2 /260C/1 YEAR SEAL DT
 MSL 1 /235C/UNLIM 03/29/04
 OPT:
 ITEM: 39
 LBL: 5A (L)T0:1750

(1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483S12
 (P)
 (2P) REV: (V) 0033317
 (20L) GSO: SHE (21L) CCO:USA
 (22L) ASO: MLA (23L) ACO: MYS

Product Affected:

TLC2254AIPWR	TLV2264IPWR
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Qualification Report

Approve Date 23-May-2022

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TLC2264AQPWRQ1	QBS Process Reference: CD3301RHHR	QBS Package Reference: TLV9064QPWRQ1
HTOL	Life Test, 150C	300 Hours	-	3/231/0	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	3/231/0	1/45/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	-
AC	Autoclave 121C	96 Hours	-	3/231/0	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	3/231/0
HBM	ESD - HBM	2000 V	1/3/0	1/3/0	-
CDM	ESD - CDM	750 V	1/3/0	1/3/0	-
LU	Latch-up	(per JESD78)	1/6/0	1/6/0	-
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	1/30/0	-
MQ	Assembly MQ	Per Site Specifications	Pass	Pass	Pass

- QBS: Qual By Similarity

- Qual Device TLC2264AQPWRQ1 is qualified at LEVEL1-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

Qualification Report

Approve Date 13-Sept-2021

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TLV2464CPWR	QBS Process Reference: CD3301RHHR	QBS Package Reference: TPS2042BD	QBS Package Reference: TPS2419DR
HTOL	Life Test, 150C	300 Hours	-	3/231/0	-	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	3/231/0	3/231/0	3/231/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	-	3/231/0
AC	Autoclave 121C	96 Hours	-	3/231/0	3/231/0	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	3/231/0	3/231/0
HBM	ESD - HBM	4000 V	1/3/0	1/3/0	-	-
CDM	ESD - CDM	1000 V	1/3/0	1/3/0	-	-
LU	Latch-up	(per JESD78)	1/6/0	1/6/0	-	-
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	1/30/0	-	-
MQ	Assembly MQ	Per Site Specifications	Pass	Pass	Pass	Pass

- QBS: Qual By Similarity

- Qual Device TLV2464CPWR is qualified at LEVEL1-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

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Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the contact shown below or your local Field Sales Representative.

Location	E-Mail
WW Change Management Team	PCN_ww_admin_team@list.ti.com

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